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- (54) **Title:** SYSTEM AND PROCESS FOR SORTING DIE FROM WAFER USING ANGLED WAFER TABLE AND ANGLED TURRET

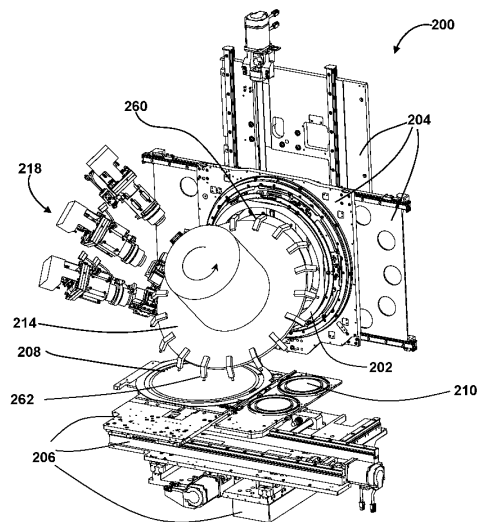


FIG. 5

- (57) **Abstract:** A system for sorting a number of dies from a wafer is provided. The system includes a first wafer table for holding a first wafer frame having the plurality of dies, wherein the first wafer table is inclined at a first angle with respect to a horizontal plane; a second wafer table to accept a plurality of dies, wherein the second wafer table is placed parallel to the horizontal plane; and a rotary turret having a plurality of heads to simultaneously pick, retain and place dies, and is positioned between the first wafer table and the second wafer table, wherein the rotary turret is inclined at a second angle with respect to the horizontal plane. Further, a process for sorting a number of dies from the wafer is also provided.

WO 2023/038572 A1